

## CUSTOMER'S IC PACKAGING PROTOTYPING REQUEST FORM

Customers are required to supply all the information needed.

- Customer's Information:

<b>COMPANY</b>	
<b>MAILING ADDRESS</b>	
<b>CONTACT NAME</b>	
<b>CONTACT NO.</b>	
<b>EMAIL ADDRESS</b>	

- For Wafer-Sawing:

<b>BASIC WAFER INFORMATION</b>			
Number of Wafer			
Wafer thickness ( m)			
Wafer size/diameter (mm)			
Wafer design type and die size (in m)	MPW (Multiple Product/Project Wafer)	Die size - same	
		*Die size - different	
	non-MPW (die size)		

- For IC Packaging:

<b>**PACKAGE TYPE</b>					
Product / Design	Length (mm)	Height (mm)	Pin Info (Pins per side)	Package Type	Number of Packages Required
1.					
2.					
3.					

**\* Please include your *wafer mapping file*.**

**\*\* Please provide your *bonding diagram* for each design**

**\*\*\* *Package footprint* for PCB design is available upon request**

- Other Service Request (Please specify):

**Selangor Human Resource Development Centre (SHRDC)**

*1A, 1st Floor, Block 2, Pusat Perniagaan WorldWide (Worldwide Business Park),*

*Jalan Tinju 13/50, Section 13, 40100 Shah Alam, Selangor Darul Ehsan*

*Tel: 03-5513 3560 || Fax: 03-5513 3490*